Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	(29/745).ccls. and (PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) with (\$plated or \$plating)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 13:14
LŻ	1	(29/847).ccls. and (PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) with (\$plated or \$plating)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 13:17
L3	2	(29/825,831,849,872).ccls. and (PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) with (\$plated or \$plating)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 13:17
L4	1	(174/250,255).ccls. and (PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) with (\$plated or \$plating)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 13:17
L5	1	(216/18,41).ccls. and (PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) with (\$plated or \$plating)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 13:18
S1	2	(mcconville-david-p).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON .	2005/09/07 10:26
S2	51	(Mcconville-david\$).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 12:24
S3	1	(Mcconville-david\$).in. and (printed adj circuit adj board) and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 12:25
S4	1	(vininski-mark).in. and (printed adj circuit adj board) and grind\$3	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:24
S5	1158	(PCB or (printed adj circuit adj board)) and (grind\$3 or machin\$3) and (indent\$4 or stamp\$3 or mark\$3) and fill\$3 and (conductive adj (paste or layer))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:26
S6	205	(PCB or (printed adj circuit adj board)) and (grind\$3 or machin\$3) and (indent\$4 or stamp\$3 or mark\$3) and (fill\$3 with (conductive adj (paste or layer)))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:33

S7	6	(PCB or (printed adj circuit adj board)) and (grind\$3 or machin\$3) and ((indent\$4 or stamp\$3 or mark\$3) same (fill\$3 with (conductive adj (paste or layer))))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:26
S8	9	("3770529"   "3956052"   "4383363"   "4622058"   "4967314"   "5346750"   "5493096"   "5638598"   "5652042").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/01 13:30
S9	1272	(PCB or (printed adj circuit adj board)) and (grind\$3 or machin\$3) and (indent\$4 or stamp\$3 or mark\$3) and ((plat\$3 or fill\$3) with (conductive adj (paste or layer or material)))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:35
S10	137	(PCB or (printed adj circuit adj board)) and (indent\$4 or stamp\$3 or mark\$3) and ((plat\$3 or fill\$3) with (conductive adj (paste or layer or material))) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:48
S11	1	("5184111").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/01 13:42
S12	6	("5950305").URPN.	USPAT	OR	ON	2006/05/01 13:43
S13	10	("4031268"   "4065197"   "4836955"   "4848829"   "4869670"   "5484186"   "5712764"   "5735041"   "5846854"   "5950305").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/01 13:44
S14	55	("2427144"   "2638660"   "2716268"   "2837619"   "2861911"   "2912745"   "2912746"   "2912748"   "3147054"   "3148098"   "3158421"   "3301730"   "3423260"   "3434208"   "3488890"   "3612745"   "3875542"   "3889363"   "4020548"   "4075420"   "4080027"   "4089734"   "4091125"   "4246563"   "4272753"   "4306925"   "4357750"   "4406062"   "4528259"   "4532152"   "4604799"   "4651417"   "4655518"   "4721550"   "4775611"   "4840702"   "4912844"   "5088009"   "5097101"   "5184111").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/01 13:44
S15	85	(PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3 or mark\$3) same ((plat\$3 or fill\$3) with (conductive adj (paste or layer or material)))) and (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/01 13:49

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S16	1	("6623651").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2006/05/02 08:08
S17	10	("3801388"   "4404059"   "4912020"   "5118386"   "5317801"   "5442144"   "5738797"   "5891367"   "6222136"   "6323434").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 08:17
S18	16	("3466206"   "3767398"   "3960561"   "4209355"   "4372804"   "4983252"   "5092032"   "5200026"   "5229549"   "5382759"   "5481795"   "5492233"   "5495665"   "5738269"   "5790377").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/02 08:20
S19	29	("5229549").URPN.	USPAT	OR	ON .	2006/05/02 08:21
S20	29	("5200026").URPN.	USPAT	OR	ON	2006/05/02 08:34
S21	5059	(PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3 or mark\$3 and groov\$3) and (plat\$3)) and (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 08:41
S22	1187	(PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3 or mark\$3) with (plat\$3)) and (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 08:41
S23	226	(PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3 or mark\$3) with (plat\$3)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 08:50
S24	63	(PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) with (\$plated or \$plating)) same (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 08:52
S25	7	(PCB or (printed adj circuit adj board)) and ((indent\$4 or stamp\$3) near (insulat\$3 adj (layer or material))) and (\$plated or \$plating) and (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 08:54
S26	318276	roller and (press\$3 or indent\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:22
S27	44248	roller near (press\$3 or indent\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:23
S28	0	(PCB or (printed adj circuit adj board)) and (roller near (press\$3 or indent\$3)) with (insulat\$3 adj (layer or material)) and (\$plated or \$plating) and (grind\$3 or machin\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:24

S29	4	(PCB or (printed adj circuit adj board)) and (roller near (press\$3 or indent\$3)) with (insulat\$3 adj (layer or material))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:25
S30	13	(PCB or (printed adj circuit adj board)) and (roller with (press\$3 or indent\$3)) with (insulat\$3 adj (layer or material))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:40
S31	259	(roller with (press\$3 or indent\$3)) with (insulat\$3 adj (layer or material))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:40
S32	259	(roller with (press\$3 or indent\$3)) with (insulat\$3 adj (layer or material))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:41
S33	114	(roller near (press\$3 or indent\$5)) with (insulat\$3 adj (layer or material))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:41
S34	4	(PCB or (printed adj circuit adj board)) and (roller near (press\$3 or indent\$5)) with (insulat\$3 adj (layer or material))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/05/02 11:42